

LINEAR TECHNOLOGY MATERIALS DECLARATION

(Engineering Calculation)

SOC

LT1217CS8#PBF

(printed on: 2014-01-19 21:53:47)

TOTAL MASS (g): 0.074802

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002081	1000000	4188.816482		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023653	975000	31628.75		
		Iron (Fe)	7439-89-6	0.000582	24000	7780.55566406		
		Phosphorus (P)	7723-14-0	0.000007	300	93.5805664062		
		Zinc (Zn)	7440-66-6	0.000017	700	227.267089844		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-98-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.024259</b>	<b>1000000</b>	<b>32430.125</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.001477	1000000	19743.5214844		
<b>External Plating Total:</b>						<b>0.001477</b>	<b>1000000</b>	<b>19743.5214844</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.000194	1000000	2593.51855469		
<b>Internal Plating Total:</b>						<b>0.000194</b>	<b>1000000</b>	<b>2593.51855469</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000919	750000	12285.7910156		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000166	250000	4090.80786133		
		<b>Die Attach Total:</b>				<b>0.001225</b>	<b>1000000</b>	<b>16376.5996094</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.006657	150000	8895.125
Bromine (Br)	40093-93-8			0.000000	0	0		
Silica (SiO2)	60676-86-0			0.036392	820000	486312		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.001110	25000	14839.2041016		
Carbon Black (C)	1333-86-4			0.000222	5000	2967.84106445		
<b>Encapsulation Total:</b>						<b>0.044381</b>	<b>1000000</b>	<b>59334.1875</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000185	1000000	2473.20068359		

TOTAL MASS (g): 0.074802